

# PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Yoshihiro Kawamura	05/18/2009
Takafumi Tsurumi	05/18/2009
Shintaro Uchida	05/18/2009
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	YAZAKI CORPORATION
<b>Street Address:</b>	4-28, Mita 1-chome, Minato-ku
<b>City:</b>	Tokyo
<b>State/Country:</b>	JAPAN
<b>Name:</b>	HONDA MOTOR CO., LTD
<b>Street Address:</b>	1-1, Minami-Aoyama 2-chome, Minato-ku
<b>City:</b>	Tokyo
<b>State/Country:</b>	JAPAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12470170
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(202)739-3001
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	2027393000
<b>Email:</b>	patents@morganlewis.com
<b>Correspondent Name:</b>	Robert J. Gaybrick
<b>Address Line 1:</b>	1111 Pennsylvania Avenue NW
<b>Address Line 4:</b>	Washington, DISTRICT OF COLUMBIA 20004
<b>ATTORNEY DOCKET NUMBER:</b>	040894-7749

CH \$40.00 12470170

**500866594**

**PATENT**  
**REEL: 022721 FRAME: 0709**

NAME OF SUBMITTER:

Robert J. Goodell

Total Attachments: 2

source=040894-7749\_Assignment#page1.tif

source=040894-7749\_Assignment#page2.tif

ATTORNEY DOCKET NO.: -  
 SOLE/JOINT INVENTION  
 (U.S. Rights Only)

### ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

#### INSULATION MEASUREMENT APPARATUS

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on \_\_\_, (Application No. \_\_\_); and

WHEREAS, YAZAKI CORPORATION, a corporation of Japan, whose post office address is 4-28, Mita 1-chome, Minato-ku, Tokyo, Japan and HONDA MOTOR CO., LTD., a corporation of Japan, whose post office address is 1-1, Minami-Aoyama 2-chome, Minato-ku, Tokyo, Japan, (hereinafter referred to as Assignee), are desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. 12/470,170, filed May 21, 2009) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor Yoshihiro KAWAMURA	Assignor's Signature <i>Yoshihiro Kawamura</i>	Date May 18, 2009
Address c/o Yazaki Parts Co., Ltd., 206-1, Nunohikibara, Makinohara-shi, Shizuoka, Japan		Citizenship Japan
Full Name of Second Assignor Takafumi TSURUMI	Assignor's Signature <i>Takafumi Tsurumi</i>	Date May 18, 2009
Address c/o HONDA R&D CO., LTD., 4-1 Chuo 1-chome, Wako-shi, Saitama, 351-0193 Japan		Citizenship Japan
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

<b>Full Name of Third Assignor</b> Shintaro UCHIDA	<b>Assignor's Signature</b> <i>Shintaro Uchida</i>	<b>Date</b> May 18, 2009
Address c/o HONDA R&D CO., LTD., 4-1 Chuo 1-chome, Wako-shi, Saitama, 351-0193 Japan		<b>Citizenship</b> Japan
<b>Full Name of Fourth Assignor</b>	<b>Assignor's Signature</b>	<b>Date</b>
Address		<b>Citizenship</b>
<b>Full Name of Fifth Assignor</b>	<b>Assignor's Signature</b>	<b>Date</b>
Address		<b>Citizenship</b>
<b>Full Name of Sixth Assignor</b>	<b>Assignor's Signature</b>	<b>Date</b>
Address		<b>Citizenship</b>
<b>Full Name of Seventh Assignor</b>	<b>Assignor's Signature</b>	<b>Date</b>
Address		<b>Citizenship</b>
<b>Full Name of Elghth Assignor</b>	<b>Assignor's Signature</b>	<b>Date</b>
Address		<b>Citizenship</b>
<b>Full Name of Ninth Assignor</b>	<b>Assignor's Signature</b>	<b>Date</b>
Address		<b>Citizenship</b>
<b>Full Name of Tenth Assignor</b>	<b>Assignor's Signature</b>	<b>Date</b>
Address		<b>Citizenship</b>
<b>Full Name of Eleventh Assignor</b>	<b>Assignor's Signature</b>	<b>Date</b>
Address		<b>Citizenship</b>
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		

1-WA/1632828.2